1k, 2k, 4k, bit EEPROMs for direct connection to serial ports

BR9010-W / BR9010F-W / BR9010FV-W / BR9010RFV-W / BR9010RFVM-W BR9020-W / BR9020F-W / BR9020FV-W / BR9020RFV-W / BR9020RFVM-W BR9040-W / BR9040F-W / BR9040FV-W / BR9040RFV-W / BR9040RFVM-W

The BR90XX series are serial EEPROMs that can be connected directly to a serial port and can be erased and written electrically. Writing and reading is performed in word units, using four types of operation commands. Communication occurs through \overline{CS} , \overline{SK} , DI, and DO pins, \overline{WC} pin control is used to initiate a write disabled state, enabling these EEPROMs to be used as one-time ROMs. During writing operation is checked via the internal status check.

Application

General-Purpose

Features

1) BR9010-W / F-W / FV-W / RFV-W / RFVM-W (1k bit) : 64 words × 16bit BR9020-W / F-W / FV-W / RFV-W / RFVM-W (2k bit) : 128words × 16bit BR9040-W / F-W / FV-W / RFV-W / RFVM-W (4k bit) : 256words × 16bit

2) Single power supply.

- 3) Serial data I/O.
- 4) Self-timed programming cycle with auto-erase.
- 5) Low supply current.

Active (5V) : 2mA (max.)

Standby (5V) : 3µA (max.) (CMOS INPUT)

6) Noise filter on the \overline{SK} pin. Write protection when the supply is low.

7) Write protection by $\overline{\text{WC}}$ pin.

8) Space Saving DIP8/SOP8/SSOP-B8/MSOP8pin Packages.

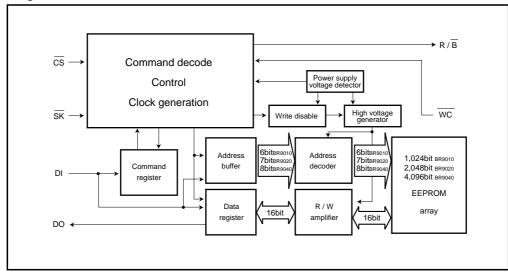
9) 100,000 erase/ write cycles endurance.

10) Provide 10 years of date retention.

11) Easy connection to serial port.

12) "FFFFh" stored in all address on shipped.

Block diagram



Terminal Function

Pin No.		Pin name	Function	
BR90xx-W/RFV-W/RFVM-W	BR90xxF-W/FV-W	Finname	FUICION	
1	3	CS	Chip Select Input	
2	4	SK	Serial Date Clock Input	
3	5	DI	Serial Date Input (Op code, address)	
4	6	DO	Serial Date Output	
5	7	GND	Ground (0V)	
6	8	WC	Write Control Input	
7	1	R/B	READY/ BUSY Status Output	
8	2	Vcc	Power Supply	

● Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Limits		Unit
Supply Voltage		Vcc	-0.3~+7.0		V
Power dissipation	BR9010-W, BR9020-W, BR9040-W		DIP8	800*1	-
	BR9010F-W, BR9020F-W, BR9040F-W	Pd	SOP8	450 ^{*2}	
	BR9010FV-W, BR9010RFV-W, BR9020FV-W, BR9020RFV-W, BR9040FV-W, BR9040RFV-W	Pa	SSOP-B8	300 ^{*3}	mW
	BR9010RFVM-W, BR9020RFVM-W, BR9040RFVM-W		MSOP8	310*4	
Storage Temperature		Tstg	-65~+125		°C
Operating Temperature		Topr	-40~+85		°C
Terminal Voltage		-	-0.3~Vcc+0.3		V

*1 Degradation is done at 8.0mW/'C for operation above Ta=25°C *2 Degradation is done at 4.5mW/'C for operation above Ta=25°C *3 Degradation is done at 3.0mW/'C for operation above Ta=25°C *4 Degradation is done at 3.1mW/'C for operation above Ta=25°C

Recommended Operating Condition (Ta=25°C)

Parameter		Symbol	Min.	Тур.	Max.	Unit		
Supply voltage	Write	Vcc	2.7	-	5.5	V		
	Read	VCC	2.0	-	5.5	V		
Input voltage		Vin	0	-	Vcc	V		

•Electrical Characteristics

Unless otherwise specified (Ta=-40~+85°C, Vcc=2.7V~5.5V)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Input LOW Voltage 1	VIL1	-	_	0.3×Vcc	V	DI pin
Input HIGH Voltage 1	VIH1	0.7×Vcc	-	-	V	DI pin
Input LOW Voltage 2	VIL2	-	_	0.2×Vcc	V	$\overline{CS}, \overline{SK}, \overline{WC}$ pin
Input HIGH Voltage 2	VIH2	0.8×Vcc	_	-	V	$\overline{CS}, \overline{SK}, \overline{WC}$ pin
Output LOW Voltage	Vol	0	_	0.4	V	IoL=2.1mA
Output HIGH Voltage	Vон	Vcc-0.4	_	Vcc	V	Іон=–0.4mA
Input Leakage Current	lu	-1	_	1	μA	VIN=0V~Vcc
Output Leakage Current	Ilo	-1	_	1	μA	Vout=0V~Vcc, CS=Vcc
Operating Current	Icc1	-	_	2	mA	fsk=2MHz, tE / W=10ms (WRITE)
	Icc2	-	_	1	mA	fsк=2MHz (READ)
Standby Current	lsв	-	_	3	μA	\overline{CS} , \overline{SK} , DI, \overline{WC} =Vcc, DO, R / \overline{B} =OPEN
Clock Frequency	fsк	_	_	2	MHz	_

Unless otherwise specified (Ta=-40~+85°C, VCC=2.7V~3.3V)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Input LOW Voltage 1	VIL1	-	-	0.3×Vcc	V	DI pin
Input HIGH Voltage 1	VIH1	0.7×Vcc	-	_	V	DI pin
Input LOW Voltage 2	VIL2	_	-	0.2×Vcc	V	$\overline{CS}, \overline{SK}, \overline{WC}$ pin
Input HIGH Voltage 2	VIH2	0.8×Vcc	_	_	V	$\overline{CS}, \overline{SK}, \overline{WC}$ pin
Output LOW Voltage	Vol	0	-	0.4	V	Ιομ=100μΑ
Output HIGH Voltage	Vон	Vcc-0.4	-	Vcc	V	Іон=-100μА
Input Leakage Current	lu	-1	_	1	μA	VIN=0V~Vcc
Output Leakage Current	Ilo	-1	-	1	μA	Vout=0V~Vcc, CS=Vcc
Operating Current	ICC1	_	-	1.5	mA	fsk=2MHz, tE / W=10ms (WRITE)
	Icc2	_	_	0.5	mA	fsк=2MHz (READ)
Standby Current	lsв	-	-	2	μA	\overline{CS} , \overline{SK} , DI, \overline{WC} =Vcc, DO, R / \overline{B} =OPEN
Clock Frequency	fsк	-	-	2	MHz	-

ns

AC Operation Characteristics

(Ta=-40~+85°C, Vcc=2.7~5.5V) Parameter Symbol Min. Тур. Max. Unit Chip Select Setup Time tcss 100 _ _ Chip Select Hold Time 100 tcsн _ _ Data In Setup Time tois 100 _ Data In Hold Time tын 100 _ _ Delay to Output High tpD1 _ _ 150 Delay to Output Low 150 tpd0 _ _ Self-Timed Program Cycle te/w 10 _ ms _ Minimum Chip Select High Time 250 _ _ tcs Data Output Disable Time(From \overline{CS}) 0 150 tон _ Clock High Time 230 _ twн _ Clock Low Time tw∟ 230 _ _ Write Control Setup Time 0 twcs _ _ Write Control Hold Time 0 twcн _ _ Clock High to Output READY/BUSY Status 150 tsv _ _

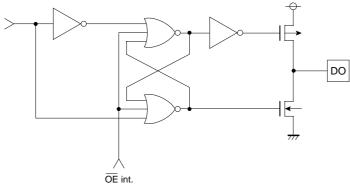


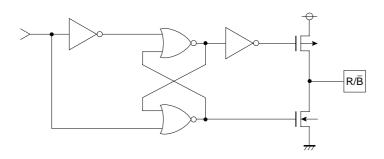
• I / O Circuit





(2) Output Circuit





Operating

(1) Instruction Code

Instruction	Start Bit	Op Code	Address	Data
READ	1010	1000	A0 A1 A2 A3 A4 A5 (A6)*2 (A7)*1	D0 D1-D14 D15 (READ DATA)
WRITE	1010	0100	A0 A1 A2 A3 A4 A5 (A6)*2 (A7)*1	D0 D1-D14 D15 (WRITE DATA)
Write Enable (WEN)	1010	0011	* * * * * * *	
Write Disable (WDS)	1010	0000	* * * * * * *	

Address and data must be transferred from LSB. * Means either VIIL or VIL BR9020-WIF-WFV-WRFV-W/RFVM-W *1= "0" BR9010-W/F-W/FV-W/RFV-W/RFVM-W *1, 2= "0"

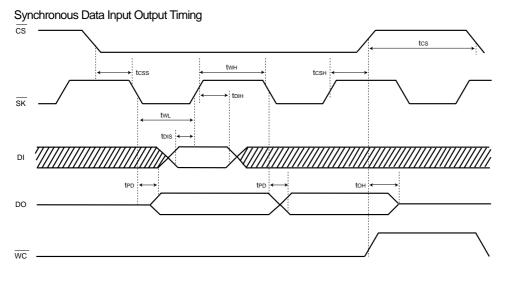


Fig.1

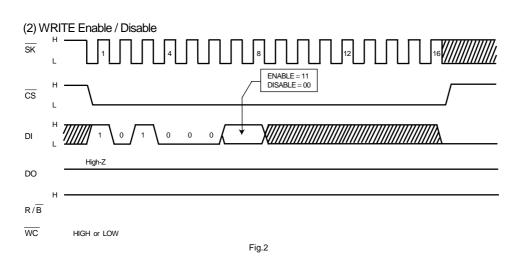
Input Data is clocked into the DI pin on the rising edge of the clock SK

• Output data is clocked out on the falling edge of the \overline{SK} clock.

• The WC pin does not have any affect on the READ, WEN and WDS operations.

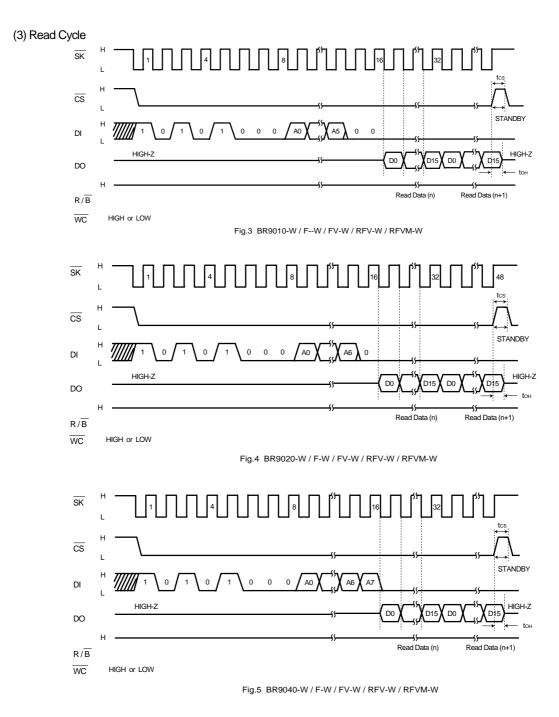
 Between instructions, CS must be brought High for greater than the minimum of tcs. If CS is maintained Low, the next instruction isn't detected.





- 1) When power is first applied, the device has been held in a reset status, with respect to the write enable, in the same way the write disable (WDS) instruction is executed. Before the write instruction is executed, the device must be received the write enable (WEN) instruction. Once the device is done, the device remains programmable until the write disable (WDS) instruction is executed or the supply is removed from the device.
- 2) It is unnecessary to add the clock after 16 th clock. If the device is recieved the clock, the device ignores the clock.
- 3) As both of the enable and disable instructions don't depend on the status of the WC pin, the state of WC isn't cared during the instruction.
- 4) The instruction is recognized after the rising edge of 8 th clock for the address following 8 clocks for the opcode, but the specified address isn't cared during the instructions.





- On the falling edge of 16 th clock, the data stored in the specified address (n) is clocked out of the DO pin. The Output DO is toggled after the internal propagation tPDO or tPD1 on the falling edge of SK. During tPD0 or tPD1, the data is the previous data or unstable, and to take in the data, tPD is needed. (Refer to Fig.1 Synchronous data input output timing.)
- 2) The data stored in the next address is clocked out of the device on the falling edge of 32nd clock. The data stored in the upper address every 16 clocks is output sequentially by the continual SK input. Also the read operation is reset by CS High.





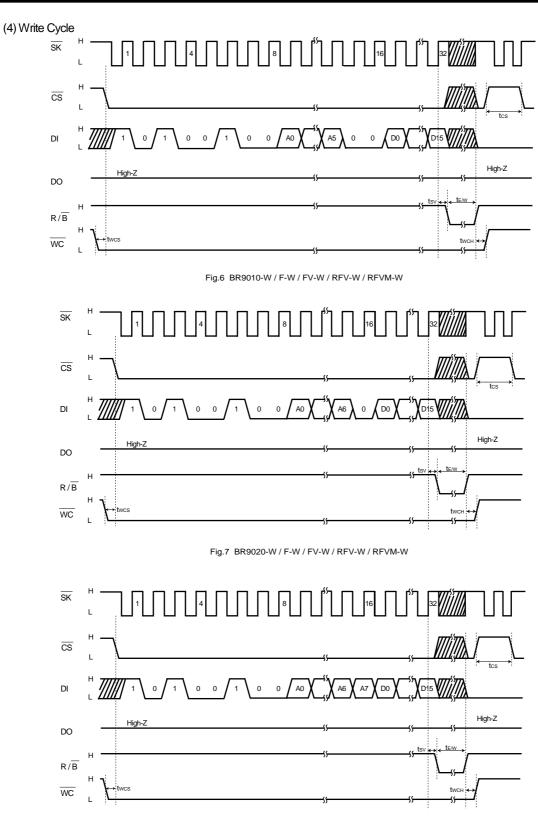


Fig.8 BR9040-W / F-W / FV-W / RFV-W / RFVM-W

ROHM

- 1) During the write instruction, CS must be brought Low. However once the write operation started, CS may be either High or Low. But in the case of connecting the WC pin to the CS pin. CS and WC must be brought Low during programming cycle. (If the WC pin is brought High during the write cycle, the write operation is halted. In that case, the data of the specified address is not guaranteed. It is necessary to rewrite it.)
- 2) After the R / B pin changed Busy to Ready, once CS is brought High, then CS keep Low ,which means the status of being able to accept an instruction. The device can take in the input from SK and DI, but in the case of keeping CS Low without being brought High once, the input is canceled until being CS High once.
- 3) At the rising edge of 32 nd clock, the R / \overline{B} pin will be driven Low after the specified time delay (tSV).
- 4) During programming, R / B is tied to Low by the device (On the rising edge of SK taken in the last data (D15), internal timer starts and automatically finished after the data of memory cell is written spending tE / W. SK could be either High or Low at the time.
- 5) After input write instruction, also the DO pin will be able to show the status of R / B, in the case that CS is falling from High to Low while SK is tied to Low. (Refer to READY / BUSY STATUS in the next page.)
- (5) READY / BUSY STATUS (on the R / B pin, the DO pin)
- 1)The DO pin outputs the READY / BUSY status of the internal part, which shows whether the device is ready to receive the next instruction or not. (High or Low)

After the write instruction is completed, if \overline{CS} is brought from high to low while \overline{SK} is Low, the DO pin outputs the internal status. (The R / B pin may be no connection.

2) When written to the memory cell, R/B status is output after tSV spent from the rising edge of 32 th clock on SK.

R / B =Low : under writing

After spending tE /W operating the internal timer, the device automatically finishes writing. During tE /W, the memory array is accessed and any instruction is not received.

R / B=High : ready

Auto programming has been completed. The device is ready to receive the next Instruction.

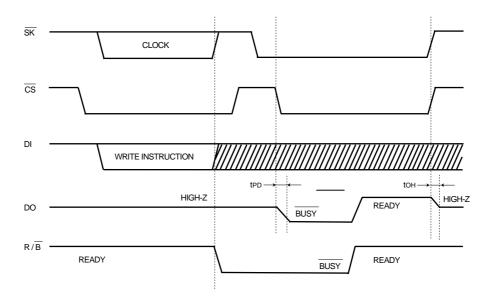


Fig.9 R / B Status Output Timing



(6) About the direct connection between the DI and DO pins

The device can be used with the DI pin connected to the DO pin directly. But when the READY / BUSY status is output, be careful about the bus conflict on the port of the controller.

Attention to Use

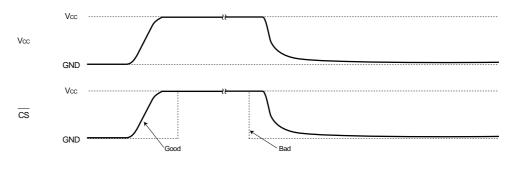
(1) Power ON / OFF

- 1) The $\overline{\text{CS}}$ is brought High during power–up and power–down.
- 2) This device is in active state while \overline{CS} is Low.
- 3) The extraordinary function or data collapse may occur in that condition because of noise etc, if power–up and power– down is done with CS brought Low.

In order to prevent above errors from happening, keep CS High during power-up and power-down.

- (Good example) CS is brought High during power–up and power-down.
 Please take more than 10ms between power–up and power-off, or the internal circuit is not always reset.
 (Bad example) CS is brought Low during power–up and power-down.
 - The CS pin is always Low in this case, the noise may force the device to make malfunction or inadvertent write.

It sometimes occurs in the case that the $\overline{\text{CS}}$ pin is Hi-Z.





(2) Noise Rejection

1) SK NOISE

If \overline{SK} line has a lot of noise for rising time of \overline{SK} , the device may recognize the noise as a clock and then clock will be shifted.

2) $\overline{\text{WC}}$ NOISE

If $\overline{\text{WC}}$ line has noise during write cycle (tE / W), there may be a chance to deny the programming.

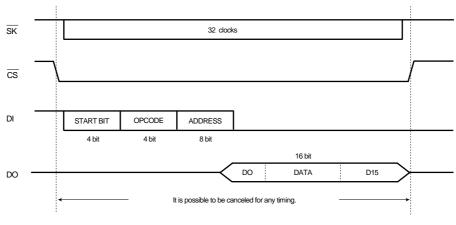
3) VCC NOISE

It recommended that capacitor is put between VCC and GND to prevent these case, since it is possible to occur malfunction by the effect of noise or surge on power line.



(3) Instruction Mode Cancel

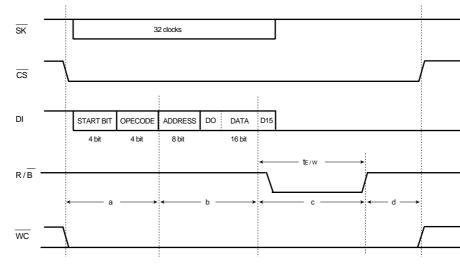




WC HIGH or LOW

Fig.11

How to cancel : \overline{CS} is brought High.



2) Write instruction



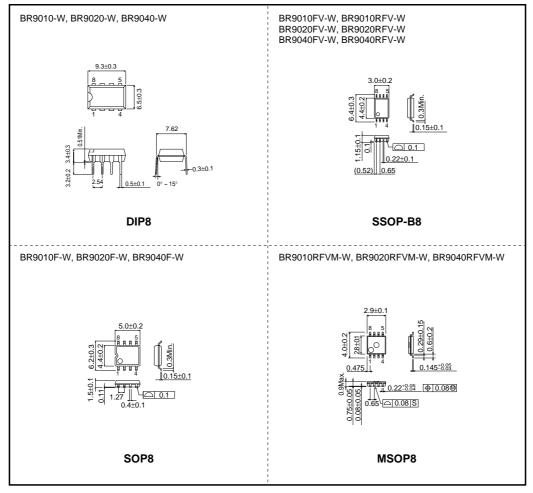
How to cancel

- a : $\overline{\text{CS}}$ is brought High to cancel the instruction, and $\overline{\text{WC}}$ may be either High or Low.
- b : In case that WC is brought High for a moment, or CS is brought High, the write instruction is canceled, the data of the specified address is not changed.
- c : When WC is brought High, or the device is powered down (But the latter way is not recommended), the instruction is canceled but the specified data is not guaranteed. Send the instruction again.
- d : When \overline{CS} is brought High during R/B High, the device is reset and ready to receive a next instruction.

NOTE : The document may be strategic technical data subject to COCOM regulations.

rohm

•External dimensions (Units : mm)





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